

IN THE CLAIMS:

Claims 1 and 13 have been amended herein. All of the pending claims 1, 3 through 6, 13, and 15 through 18 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1. (Currently Amended) A resist removal method used in an automolding system comprising:
providing an automolding system having a laser;
providing a substrate having a surface;
forming resist on at least a portion of the surface; and
removing at least a portion of the resist from the substrate using the laser used in the automolding system;
scanning the substrate using a laser in the automolding system for irregularities from removing the layer of resist.
and
placing the substrate in the molding portion of the automolding system for encapsulation of a portion thereof.
2. (Cancelled)
3. (Previously Presented) The method according to claim 1 wherein the laser comprises one of an Nd:YAG laser and an excimer laser.
4. (Previously Presented) The method according to claim 1 wherein the substrate comprises a ball-grid-array substrate.

5. (Original) The method according to claim 1 further comprising a vision system for detecting resist.

6. (Previously Presented) The method according to claim 5 wherein the vision system comprises:
providing a laser scanning system; and
detecting changes in a pattern of the substrate.

7.-12. (Cancelled)

13. (Currently Amended) A method of fabricating a semiconductor device in an automolding system comprising:
providing an automolding system having a laser for etching resist from a surface of a substrate;
providing a substrate having a surface to be etched by the laser in the automolding system;
forming resist on at least a portion of the surface;
laser etching the resist from at least a portion of the surface of the substrate using the laser in the automolding system;
marking a surface of the semiconductor die using the laser in the molding system; and
encapsulating the substrate in the molding portion of the automolding system.

14. (Cancelled)

15. (Previously Presented) The method according to claim 13 wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

16. (Previously Presented) The method according to claim 13 wherein the substrate comprises a ball-grid-array substrate.

17. (Original) The method according to claim 13 further comprising a vision system for detecting resist.

18. (Previously Presented) The method according to claim 17 wherein the vision system comprises:

providing a laser scanning system; and

detecting changes in a pattern of the substrate.

19.-23. (Cancelled)